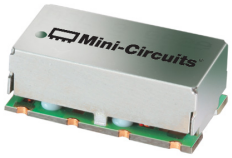
Surface Mount

Bandpass Filter

SXBP-820+

50Ω 769 to 872 MHz



Generic photo used for illustration purposes only

CASE STYLE: HF1139

+RoHS Compliant

The +Suffix identifies RoHS Compliance. See our web site for RoHS Compliance methodologies and qualifications

Maximum Ratings

Operating Temperature	-40°C to 85°C
Storage Temperature	-55°C to 100°C
RF Power Input	0.5W Max.

Permanent damage may occur if any of these limits are exceeded.

Pin Connections

INPUT	1
OUTPUT	8
GROUND	2, 3, 4, 5, 6, 7

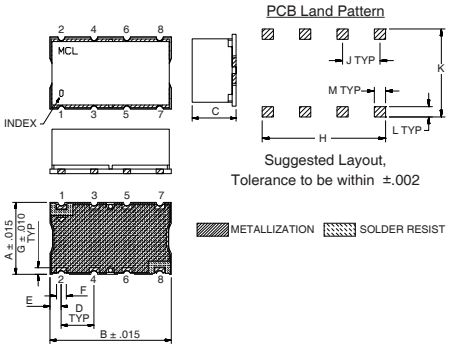
Features

- High Rejection
- Flat Group Delay
- Shielded case
- Aqueous washable

Applications

- Mobile TV
- Receivers / Transmitters
- Harmonic rejection

Outline Drawing



Outline Dimensions (inch / mm)

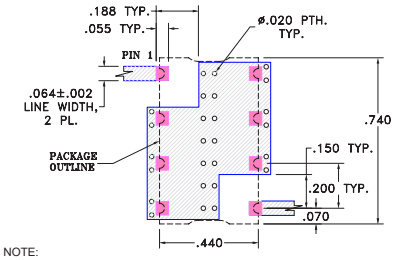
A	B	C	D	E	F
.440	.740	.27	.200	.07	.060
11.18	18.80	6.86	5.08	1.78	1.52

G	H	J	K	L	M	wt.
.040	.660	.200	.470	.055	.060	grams
1.02	16.76	5.08	11.94	1.40	1.52	3.0

Note: Please refer to case style drawing for details

Demo Board MCL P/N: TB-368

Suggested PCB Layout (PL-230)



NOTE:

1. TRACE WIDTH IS SHOWN FOR FR4 WITH DIELECTRIC THICKNESS. .025" ± .002". COPPER: 1/2 OZ. EACH SIDE. FOR OTHER MATERIALS TRACE WIDTH MAY NEED TO BE MODIFIED.
2. BOTTOM SIDE OF THE PCB IS CONTINUOUS GROUND PLANE.

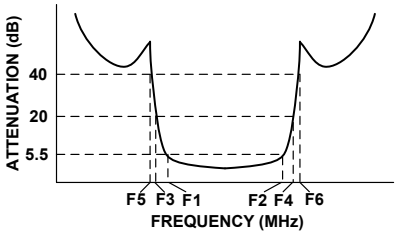
DENOTES PCB COPPER LAYOUT

DENOTES COPPER LAND PATTERN FREE OF SOLDER MASK

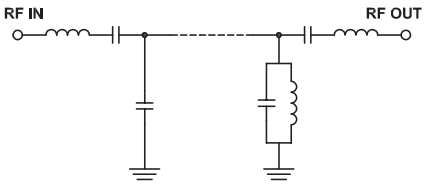
Bandpass Filter Electrical Specifications (T_{AMB}= 25°C)

CENTER FREQ. (MHz)	PASSBAND (MHz) (Loss < 5.5dB)	STOPBANDS (MHz)				VSWR (:1)		
		Loss > 20dB		Loss > 40dB		Passband		Stopband
Fc	F1 - F2	F3	F4	F5	F6	Typ.	Max.	Typ.
820	769 - 872	550	920	450	1000 - 2600	1.7	2.3	20

Typical Frequency Response



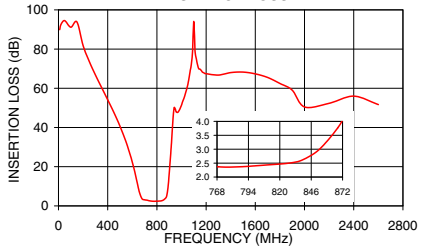
Functional Schematic



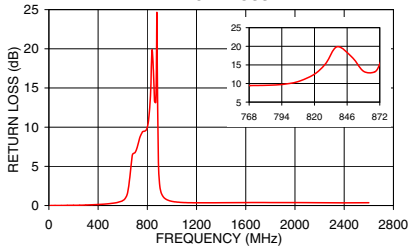
Typical Performance Data at 25°C

Frequency (MHz)	Insertion Loss (dB) $\bar{x}$	Insertion Loss (dB) σ	Return Loss (dB)	Frequency (MHz)	Group Delay (nSec)
10	89.91	3.72	0.01	760	5.22
100	91.17	3.09	0.01	766	5.27
450	47.71	0.32	0.18	769	5.30
550	32.51	0.37	0.46	772	5.33
619	17.67	0.77	0.88	778	5.41
640	11.85	0.92	1.63	790	5.62
658	6.91	0.76	3.61	799	5.83
769	2.37	0.19	9.46	808	6.09
799	2.40	0.13	9.95	820	6.56
820	2.47	0.11	12.51	829	7.13
850	2.90	0.28	17.04	838	8.04
872	4.05	0.30	15.27	850	8.96
880	5.13	0.54	19.23	859	9.11
890	9.27	1.73	5.58	868	8.91
900	16.48	2.56	2.71	872	8.73
920	33.32	3.78	1.36	874	8.61
1000	51.37	0.64	0.53	876	8.46
2600	51.67	0.63	0.36	880	8.01

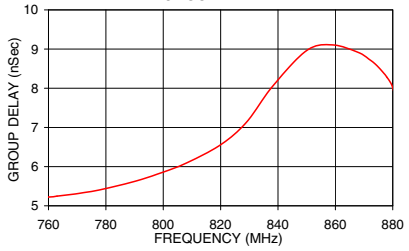
SXBP-820+
INSERTION LOSS



SXBP-820+
RETURN LOSS



SXBP-820+
GROUP DELAY



Notes

A. Performance and quality attributes and conditions not expressly stated in this specification document are intended to be excluded and do not form a part of this specification document.
B. Electrical specifications and performance data contained in this specification document are based on Mini-Circuit's applicable established test performance criteria and measurement instructions.
C. The parts covered by this specification document are subject to Mini-Circuits standard limited warranty and terms and conditions (collectively, "Standard Terms"); Purchasers of this part are entitled to the rights and benefits contained therein. For a full statement of the Standard Terms and the exclusive rights and remedies thereunder, please visit Mini-Circuits' website at www.minicircuits.com/MCLStore/terms.jsp

CHECK PRINT *(FOR INTERNAL USE ONLY)*			
MODEL: SXBP-820+:			
NAME (PRINT)	SIGNATURE	DATE	FILE SIZE
GALINA DUBONIN	Gd.	09 Feb', 2009	170 KB
URJITA ENGINEER		10 Feb', 2009	
DAVID HAIMOVICH	DH	09 Feb', 2009	
APPROVED BY:	HK	13 Feb', 2009	

Surface Mount Band Pass Filter SXBP-820+

Typical Performance Data

FREQUENCY (MHz)	INSERTION LOSS (dB)	RETURN LOSS (dB)
10	89.91	0.01
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872	4.05	15.27
880	5.13	19.23
890	9.27	5.58
900	16.48	2.71
920	33.32	1.36
1000	51.37	0.53
2600	51.67	0.36

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760	5.22
766	5.27
769	5.30
772	5.33
778	5.41
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808	6.09
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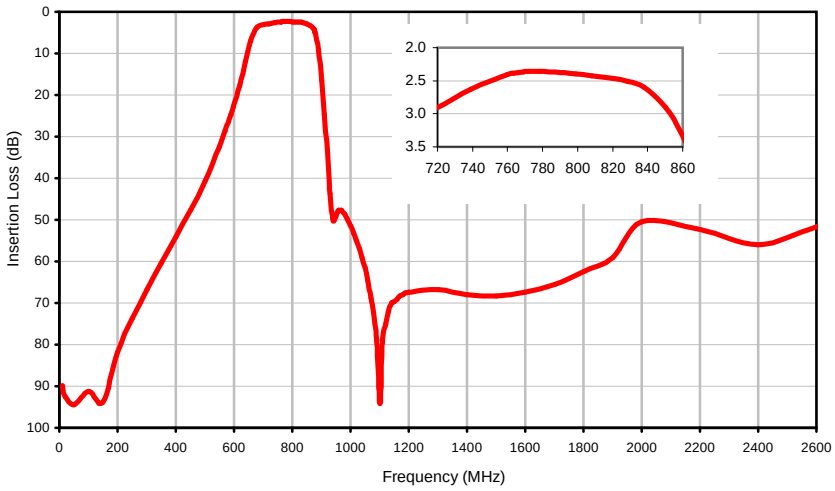
850	8.96
859	9.11
868	8.91
872	8.73
874	8.61
876	8.46
880	8.01

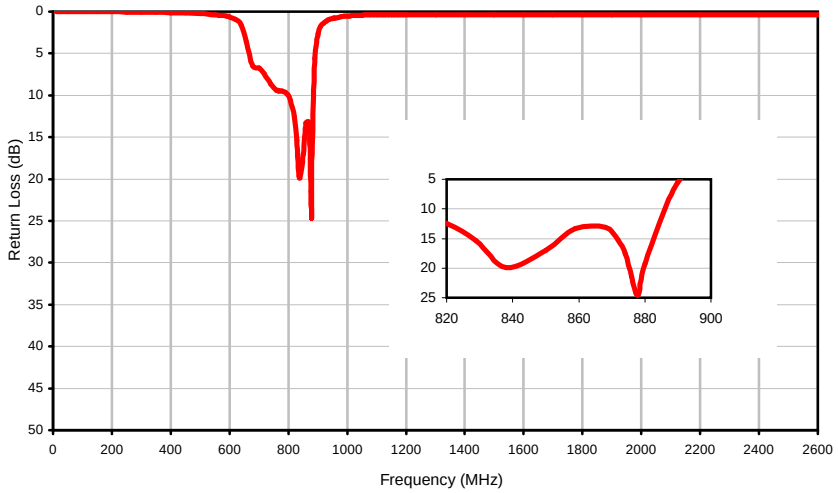
Surface Mount Band Pass Filter SXBP-820+

Typical Performance Curves

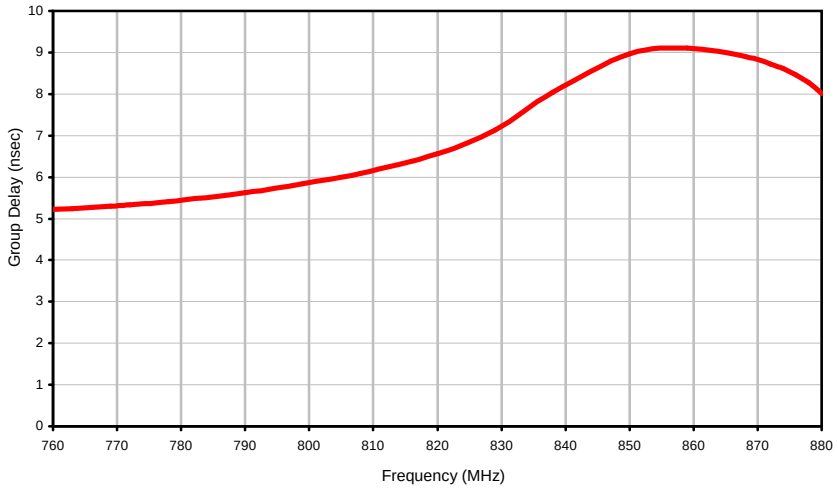
Insertion Loss



Return Loss



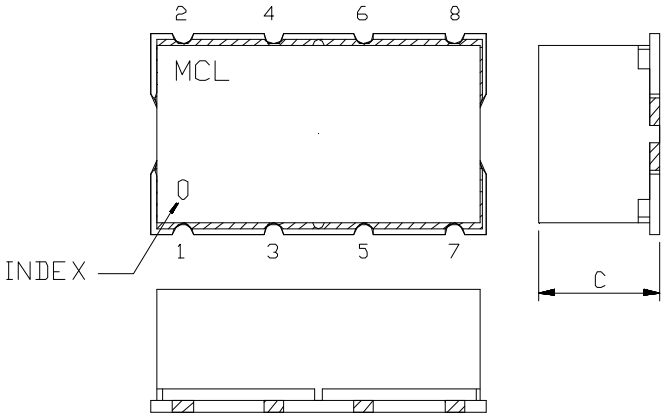
Group Delay

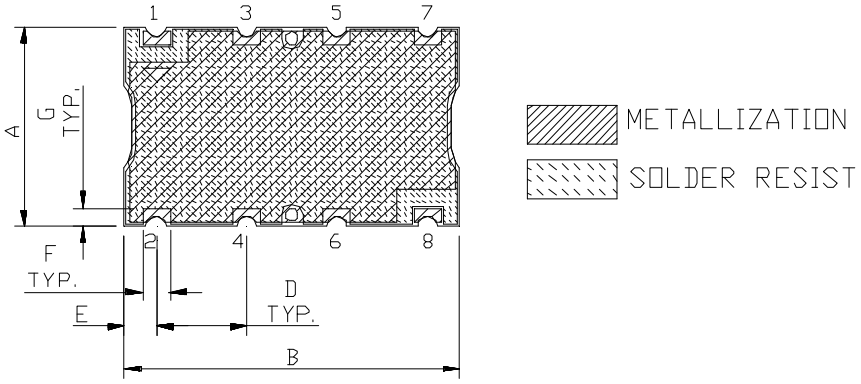


Case Style HF

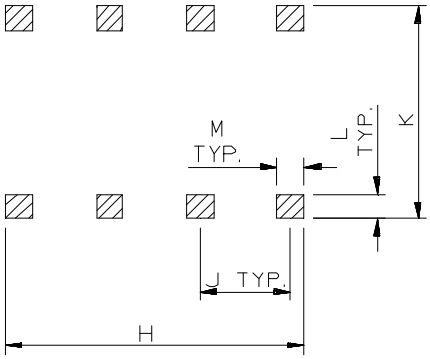
HF1139

Outline Dimensions





PCB Land Pattern



CASE #	A	B	C	D	E	F	G	H	J	K	L	M	WT. GRAMS
HF1139	.44 (11.18)	.74 (18.80)	.27 (6.86)	.200 (5.08)	.07 (1.78)	.060 (1.52)	.040 (1.02)	.660 (16.76)	.200 (5.08)	.470 (11.94)	.055 (1.40)	.060 (1.52)	3.0

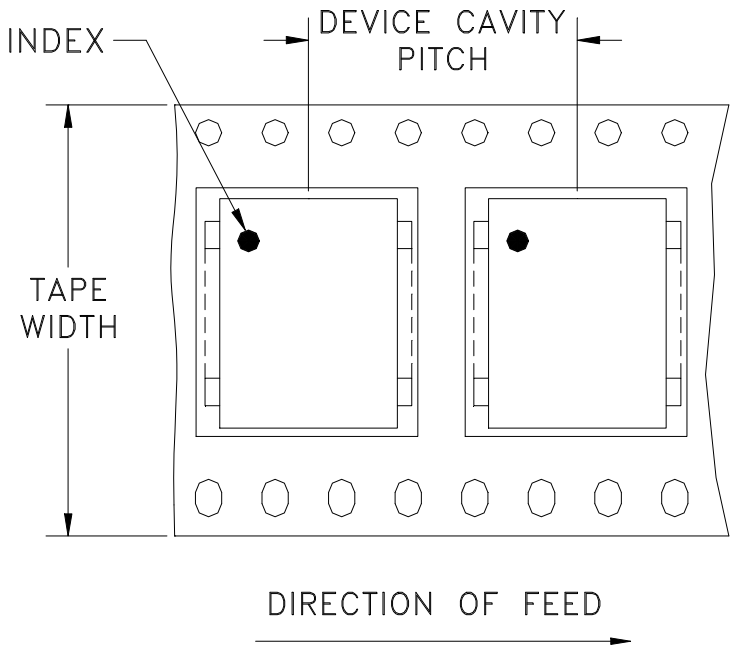
Dimensions are in inches (mm). Tolerances: 2 Pl. ±.015"; 3 Pl. ±.01"

Notes:

1. Case material: Nickel-Silver alloy.
2. Base: Printed wiring laminate.
3. Termination finish:
   For RoHS Case Styles: 2-5 µ inch (.05-.13 microns) Gold over 120-240 µ inch (3.05-6.10 microns) Nickel plate.
   For RoHS-5 Case Styles: Tin-Lead plate.

Tape & Reel Packaging TR-F5

DEVICE ORIENTATION IN T&R



Tape Width, mm	Device Cavity Pitch, mm	Reel Size, inches	Devices per Reel
32	16	13	500

Mini-Circuits carrier tape materials provide protection from ESD (Electro-Static Discharge) during handling and transportation. Tapes are static dissipative and comply with industry standards EIA-481/EIA-541.

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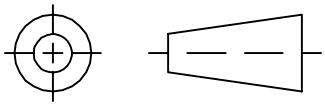
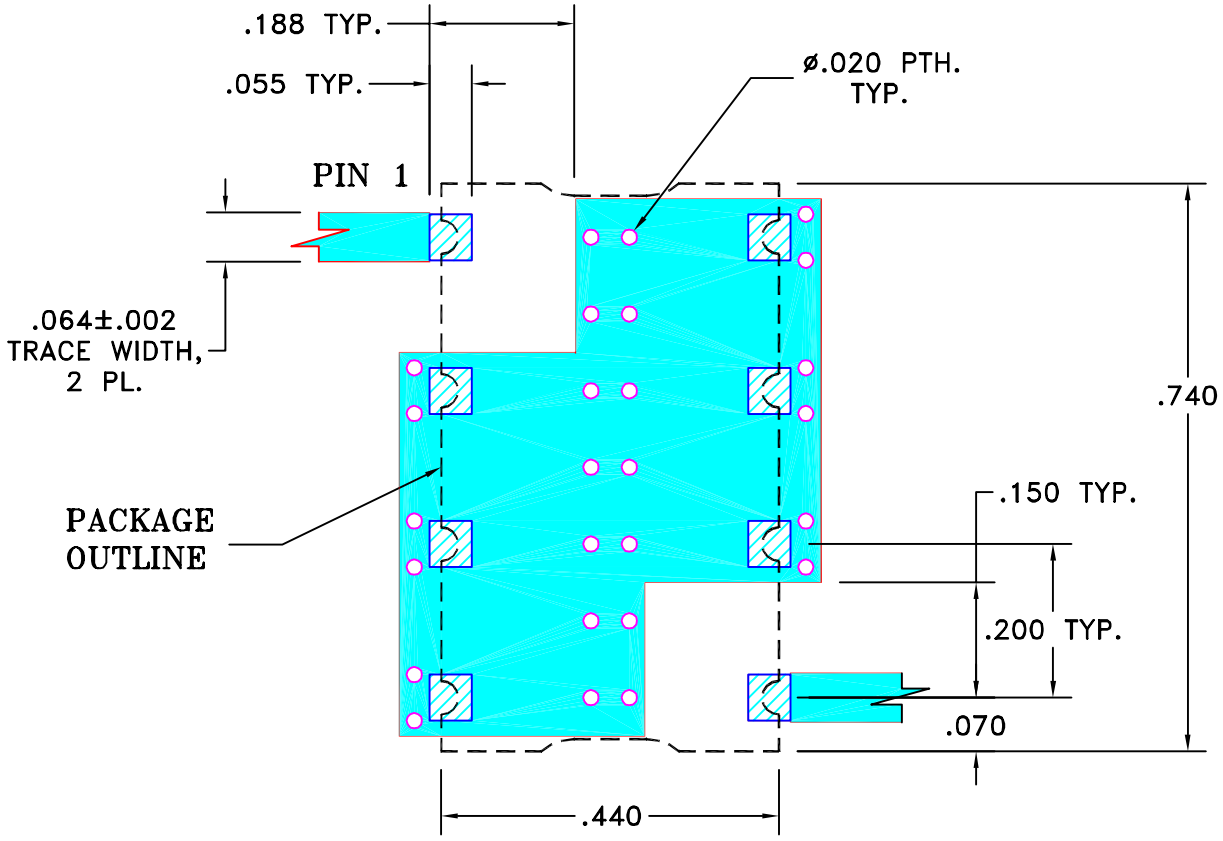
THIRD ANGLE PROJECTION



REVISIONS

REV	ECN No.	DESCRIPTION	DATE	DR	AUTH
OR	M101757	NEW RELEASE (FROM RAVON)	11/05	DK	HH
OR	R62293	NEW RELEASE (FROM RAVON)	11/05	DK	HH

SUGGESTED MOUNTING CONFIGURATION
FOR HF1139 CASE STYLE, cr PIN CONNECTION, 50 OHM.



NOTE:

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   FOR OTHER MATERIALS TRACE WIDTH MAY NEED TO BE MODIFIED.
2. BOTTOM SIDE OF THE PCB IS CONTINUOUS GROUND PLANE.

DENOTES PCB COPPER LAYOUT WITH SMOBC (SOLDER MASK OVER BARE COPPER)

DENOTES COPPER LAND PATTERN FREE OF SOLDER MASK

UNLESS OTHERWISE SPECIFIED		INITIALS	DATE
DIMENSIONS ARE IN INCHES	DRAWN	DK (RAVON)	29 NOV 05
TOLERANCES ON:	CHECKED	RZ (RAVON)	29 NOV 05
2 PL DECIMALS ±	APPROVED	HH (RAVON)	29 NOV 05
3 PL DECIMALS ± .005			
ANGLES ±			
FRACTIONS ±			

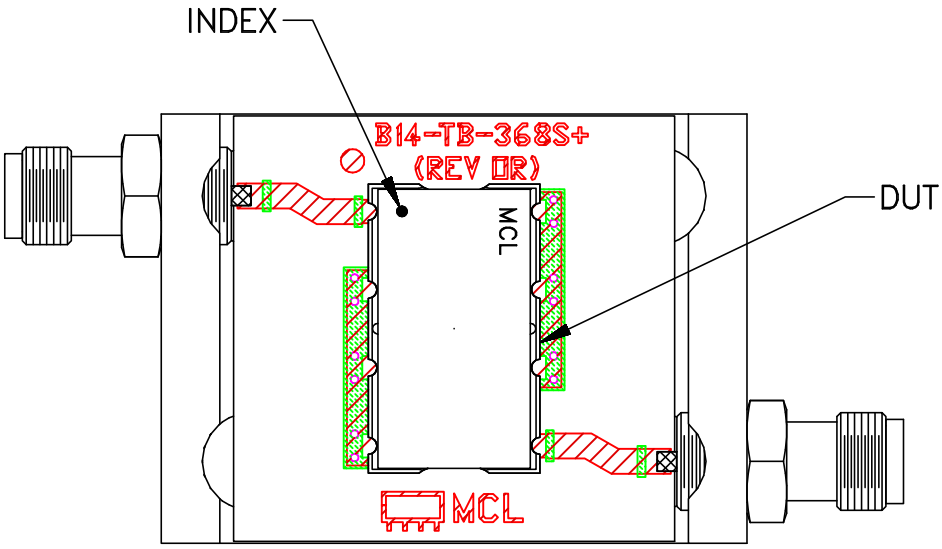
ASHEETA1.DWG REV:A DATE:01/12/95

Mini-Circuits® 13 Neptune Avenue Brooklyn NY 11235

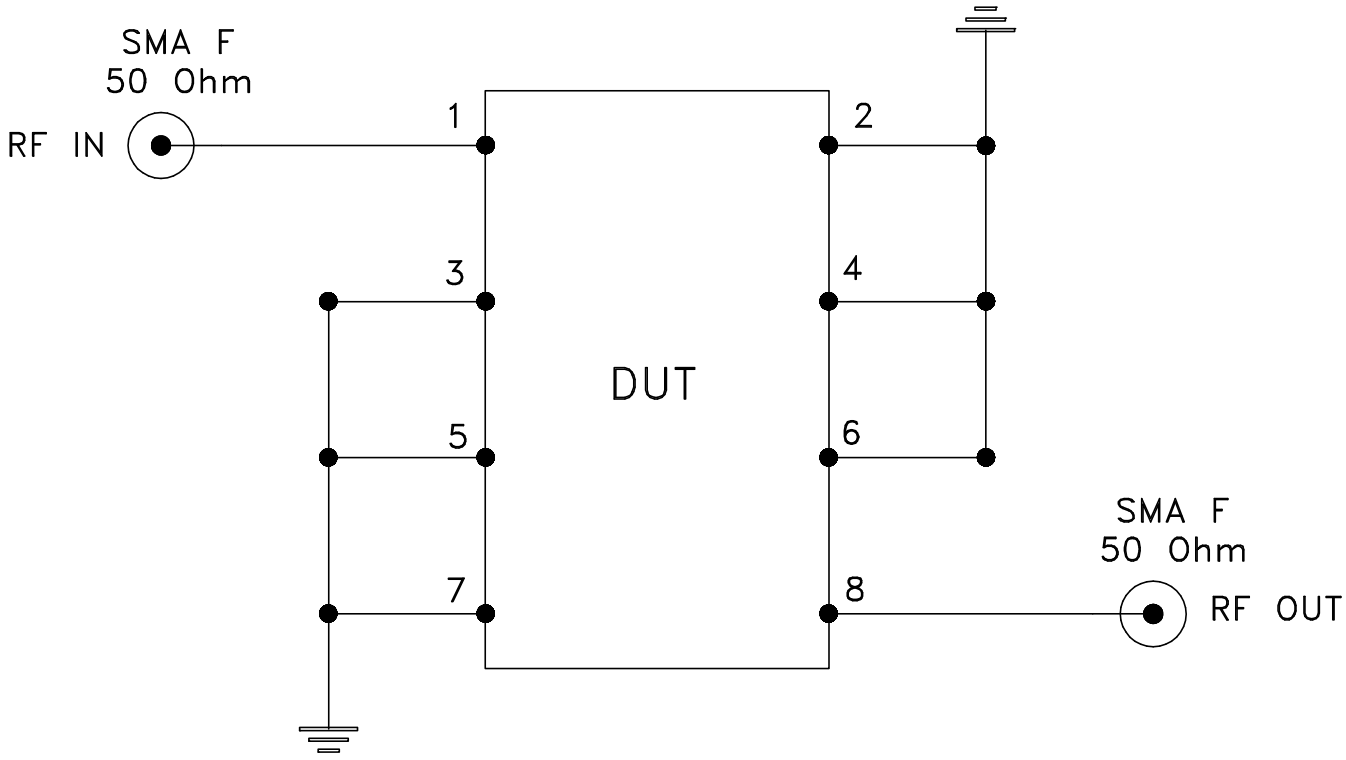
PL, cr, HF1139, SCLF, TB-368

SIZE	CODE IDENT	DRAWING NO:	REV:
A	15542	98-PL-230	OR
FILE: 98PL230	SCALE: 4:1	SHEET: 1 OF 1	

Evaluation Board and Circuit



TB-368



Schematic Diagram

Notes:
1. SMA Female connectors.
2. PCB Material: ROGERS R04350B or equivalent, Dielectric Constant=3.5, Thickness=.030 inch.

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Environmental Specifications ENV02T1

All Mini-Circuits products are manufactured under exacting quality assurance and control standards, and are capable of meeting published specifications after being subjected to any or all of the following physical and environmental test.

Specification	Test/Inspection Condition	Reference/Spec
Operating Temperature	-40° to 85°C Ambient Environment	Individual Model Data Sheet
Storage Temperature	-55° to 100° C Ambient Environment	Individual Model Data Sheet
Humidity	90 to 95% RH, 240 hours, 50°C	MIL-STD-202, Method 103, Condition A, Except 50°C and end-point electrical test done within 12 hours
Thermal Shock	-55° to 100°C, 100 cycles	MIL-STD-202, Method 107, Condition A-3, except +100°C
Solder Reflow Heat	Sn-Pb Eutetic Process: 225°C peak Pb-Free Process 245° - 250°C peak	J-STD-020, Table 4-1, 4-2 and 5-2, Figure 5-1
Solderability	10X Magnification	J-STD-002, 95% Coverage
Vibration (High Frequency)	20g peak, 10-2000 Hz, 12 times in each of three perpendicular directions (total 36)	MIL-STD-202, Method 204, Condition D
Mechanical Shock	50g, 11 ms, 1/2-sine, 18 shocks: 3 each direction, each of 3 axes	MIL-STD-202, Method 213, Condition A
Marking Resistance to Solvents	Isopropyl alcohol + mineral spirits at 25°C; terpene defluxer at 25°C; distilled water + proylene glycol monomethyl ether + monoethanolamine at 63°C to 70°C	MIL-STD-202, Method 215